



Mindspeed(R) Introduces Next-Generation Family of System-on-Chip Carrier Access VoIP Processors

Comcerto(R) 300 Series Processors Enable Cost-Effective Migration from Class-5 TDM Voice Networks to Next-Generation IP-Based Access with Carrier-Class Performance

NEWPORT BEACH, Calif., Jan 22, 2008 (BUSINESS WIRE) -- Mindspeed Technologies, Inc. (NASDAQ: MSPD), a leading supplier of semiconductor solutions for network infrastructure applications, today announced a new family of highly-integrated voice-over-IP (VoIP) processors designed to enable the migration of copper loop voice access networks from traditional Class 5 time-division multiplexing (TDM) equipment to next-generation VoIP multiservice access nodes (MSANs).

The Comcerto 300 Series of access VoIP processors combines the company's field-proven system-on-chip (SoC) architecture and carrier-class software, enabling equipment manufacturers to quickly and efficiently develop VoIP-to-Ethernet line cards for MSANs, Ethernet/IP-enabled digital subscriber line access multiplexors (IP-DSLAMs) and next-generation digital loop carriers (DLCs).

"Our Comcerto 300 Series breaks new ground in what we believe is an emerging high-volume market opportunity and has already been selected by several leading vendors for their next-generation access platforms," said Tom Medrek, senior vice president and general manager of Mindspeed's multiservice access business unit.

"The opportunity to dramatically lower capital and maintenance costs while offering multiple revenue-generating services is encouraging carriers to deploy next-generation IP-packet access networks. We believe the next major wave of VoIP adoption will replace traditional Class 5 TDM switching with cost-effective multi-service access equipment, offering subscribers triple-play voice, video and data services," Medrek added.

Comcerto 300 Series access processors integrate a complete media access gateway in a single device by combining signaling and control processing, packet processing and a rich set of interfaces and features. By enabling "VoIP on a line card" the Comcerto 300 Series reduces system complexity and leverages the Ethernet-based access equipment architectures that already support xDSL termination line cards. The device family is also well suited for IP-PBX applications.

Technical Details

The Comcerto 300 Series device architecture incorporates two separate ARM11 processor cores and a DSP array coupled through a shared memory subsystem to simultaneously provide real-time, low-latency media processing, as well as call control and call setup functions. One ARM11 is dedicated to media stream packet processing, while the second ARM11 is dedicated to the signaling, call-control and board management functions. This functional division greatly simplifies software development.

Dual independent Gigabit Ethernet interfaces with integrated SerDes offer a rich set of configuration options including sGMII supporting direct backplane connectivity for high availability, high-reliability MSAN and IP-DSLAM architectures using "dual-star" Ethernet switch fabric architectures. The device also provides the ability to generate TDM clocks which are frequency-synchronized to a TDM network-generated packet stream.

Comcerto 300 Series processors are designed to support narrowband plain-old telephone service (POTS) line cards from 24 to more than 150 channels including echo cancellation, tone detection and other narrowband copper loop telephony features. Dual SPI, i2C, two UARTs, 32 GPIOs and an expansion bus connect to a wide array of devices.

Mindspeed also offers a Comcerto 300 Series design kit which includes a silicon support package software bundle (SiSP) for both VxWorks(R) and Linux(R). An available Comcerto 300 Series evaluation module (EVM) provides all necessary memory, a TSI, four FXS POTS lines, one FXO trunk line, two 10/100/1000BaseT Ethernet interfaces (with SFP option for optical connectivity), and a T1/E1 interface. The EVM also includes a system expansion connector designed to mate with Zarlink Semiconductor's Legerity SLIC/SLAC EVMs, allowing customers to quickly and easily configure VoIP-enabled POTS systems from 8 to 72 ports.

Pricing and Availability

Comcerto 300 Series M823xx devices are available in five performance levels and two packaging options (RoHS/standard). Packaged in a 23x23mm, 1mm pitch BGA, volume production is scheduled in the third calendar quarter of 2008, with prices

ranging between \$36 and \$99 per unit in OEM quantities. Samples are available now.

About Mindspeed Technologies(R)

Mindspeed Technologies, Inc. designs, develops and sells semiconductor networking solutions for communications applications in enterprise, access, metropolitan and wide area networks.

The company's three key product families include high-performance analog transmission and switching solutions, multiservice access products designed to support voice and data services across wireline and wireless networks, and WAN communications solutions including T/E carrier physical-layer and link-layer devices as well as ATM/MPLS network processors.

Mindspeed's products are used in a wide variety of network infrastructure equipment, including voice and media gateways, high-speed routers, switches, access multiplexers, cross-connect systems, add-drop multiplexers and digital loop carrier equipment.

To learn more, visit us at www.mindspeed.com.

Safe Harbor Statement

This press release contains statements relating to Mindspeed, and our future results, including certain projections and business trends, that are "forward-looking statements" as defined in the Private Securities Litigation Reform Act of 1995. Actual results, and actual events that occur, may differ materially from those projected as a result of certain risks and uncertainties. These risks and uncertainties include, but are not limited to: market demand for our new and existing products and our ability to increase our revenues; our ability to maintain operating expenses within anticipated levels; our ability to reduce our cash consumption; availability and terms of capital needed for our business; constraints in the supply of wafers and other product components from our third-party manufacturers; our ability to successfully and cost effectively establish and manage operations in foreign jurisdictions; our ability to attract and retain qualified personnel; successful development and introduction of new products; our ability to successfully integrate acquired businesses and realize the anticipated benefits from such acquisitions; our ability to obtain design wins and develop revenues from them; pricing pressures and other competitive factors; industry consolidation; order and shipment uncertainty; changes in our customers' inventory levels and inventory management practices; fluctuations in manufacturing yields; product defects; and intellectual property infringement claims by others and the ability to protect our intellectual property, as well as other risks and uncertainties, including those detailed from time to time in our Securities and Exchange Commission filings.

SOURCE: Mindspeed Technologies, Inc.

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